Summary and Outlook

Summary

- SRS Imaging of silicon with telecom-wavelength laser:
  Long penetration depth & high sensitivity
- Breakthrough in Silicon Imaging:
  Achieved 3D non-destructive imaging of strain inside silicon, a feat unattainable with traditional techniques.

Future Research Directions:

- 3D temperature mapping
- Improve system performance:
  - Increase laser power.
  - Optimize numerical aperture (NA) of microscopy.
- Broader applications:
  Explore wider applications in the semiconductor inspection and more!